Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HP 5800-48G-PoE+ Sw w 1 Intf Slt(JC104B)
HP 5800-48G Switch w 1 Intf Slot(JC105B)
HP 5800-48G-PoE+ TAA Sw w 1 Slot(JG257B)
HP 5800-48G TAA Sw w 1 Intf Slot(JG258B)
HP A5800-48G-PoE+ Switch with 1 Interface Slot（JC104A）
HP A5800-48G Switch with 1 Interface Slot（JC105A）
HP A5800-48G-PoE+ TAA-compliant Switch with 1 Interface Slot（JG257A）
HP A5800-48G TAA-compliant Switch with 1 Interface Slot（JG258A）

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sqcm	4
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardantsweighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink,	Include the cartridges, print heads, tubes, vent	0

including liquids, semi-liquids (gel/paste) and toner	chambers, and service stations.	
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew the screws on mounting angle 1, and then remove mounting angle 1.
2. Unscrew the screws on card 2, and then remove card 2.
3. Unscrew the screws on metal panel 3, and then remove metal panel 3.
4. Remove AC cable holder 4.
5. Unscrew the screws on cover 5, and then remove cover 5 from the enclosure.
6. Unscrew the screws on fans 7, and then remover fans 7 from the enclosure.
7. Unscrew the screws on fans 10, and then remover fans 10 from the enclosure.
8. Remove AC socket 8 from the enclosure.
9. Unscrew the screws on power unit 9, and remover power unit 9 from the enclosure.
10. Unscrew the screws on radiator 11, and remove radiator 11 from mother PCB 13.
11. Unscrew the screws on daughter PCB 12, and remove daughter PCB 12 from mother PCB 13.
12. Unscrew the screws on mother PCB 13, and then remove mother PCB 13 from the enclosure.
13. Remove front panel set 14 from the enclosure.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations)

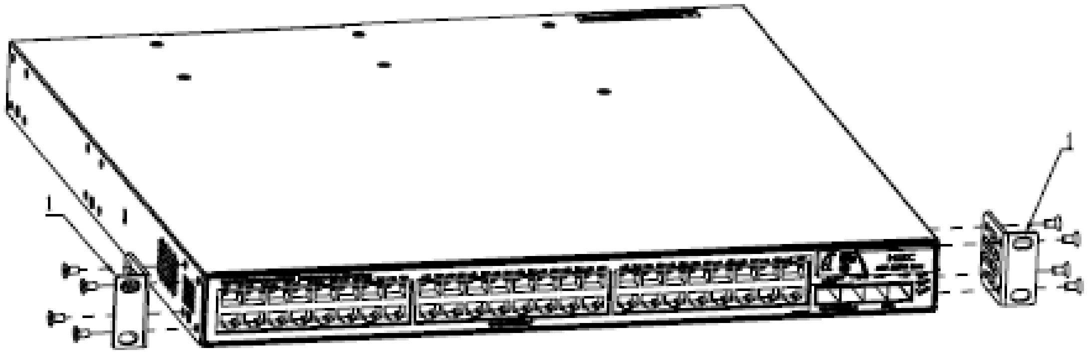

Figure 1Remove mounting angle

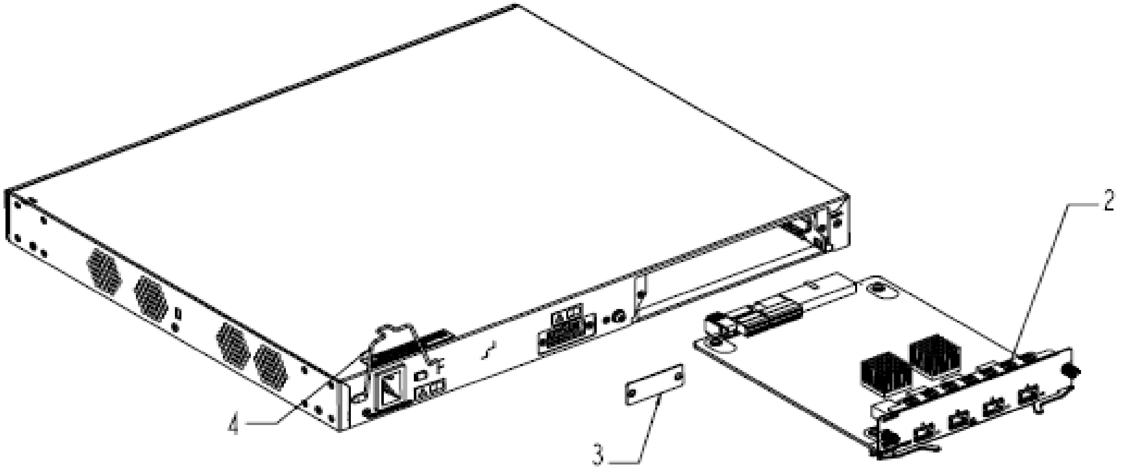

Figure 2 Treatment to the product（I）

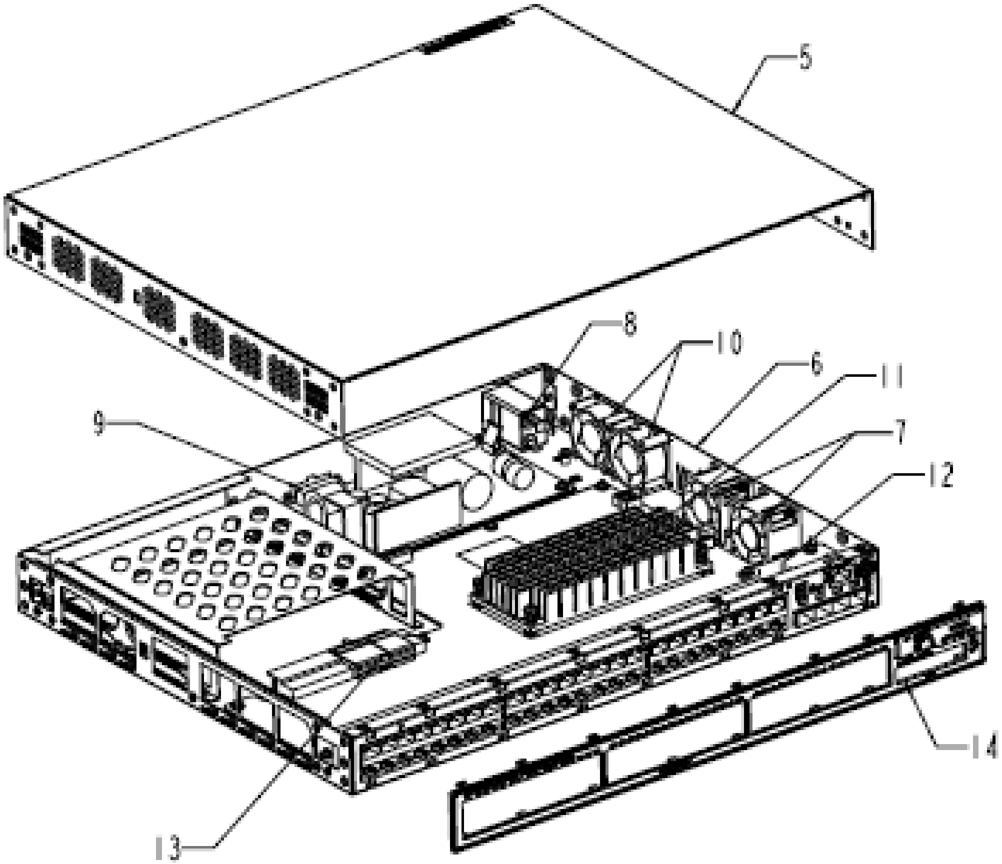

Figure 3 Treatment to the product（II）

3.3 Material of the facility built

Facility	Components	Material	Weight(g)	Weight percentage	Selective treatment for materials and components	Details
1		Fe	78	1.2%		Fe recycling
2		Complex PCB	650	10.3%	The surface of PCB is greater than 10 square centimeters;	
3		Fe	4	0.1%		Fe recycling
4		Fe	4	0.1%		Fe recycling
5		Fe	1623	25.8%		Fe recycling
6		Fe	1819	/		Fe recycling
7		PC	64	1.0%		PC recycling
8		Cable	/	/		
9		Complex PCB	350	5.6%	The surface of PCB is greater than 10 square centimeters;	
10		PC	66	1.0%		PC recycling
11		Al	218	3.5%		Al recycling
12		Complex PCB	30	0.5%	The surface of PCB is greater than 10 square centimeters;	
13		Complex PCB	1340	21.3%	The surface of PCB is greater than 10 square centimeters;	
14		PC	40	0.6%		PC recycling

4.0 Revised record

Date	Version	Author	Modify content
2014.11.20	V0	Wu Xuejun	Initial version